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Dimensions	
Chip Size	2225
L	5.588mm +/-0.381mm (0.22 in +/-0.015 in)
W	6.35mm +/-0.381mm (0.25 in +/-0.015 in)
T	1.778mm MAX (0.07 in MAX)

Packaging Specifications	
Packaging	Waffle
Packaging Quantity	25000

General Information	
Series	SMD Mil PRF123
Style	SMD Chip
Description	SMD Chip, Ultra Stable
RoHS	No
Prop 65	⚠ WARNING: Cancer and reproductive harm - http://www.p65warnings.ca.gov .
SCIP Number	8780dfd-a0b3-4664-b80c-18c07cfab0d1
Termination	Tin
Failure Rate	N/A
AEC-Q200	No
Shelf Life	78 Weeks
MSL	1

Specifications	
Capacitance	3300 pF
Capacitance Tolerance	10%
Voltage DC	50 VDC
Dielectric Withstanding Voltage	125 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	BP
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1kHz 1.0Vms
Dissipation Factor	2.5%
Insulation Resistance	100 GOhms

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

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